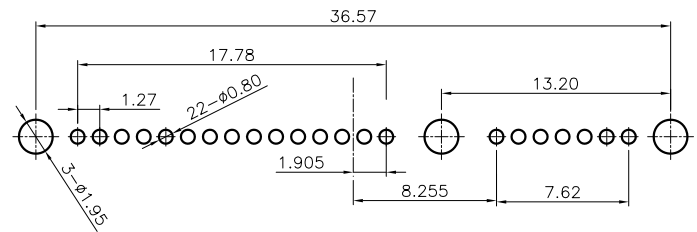
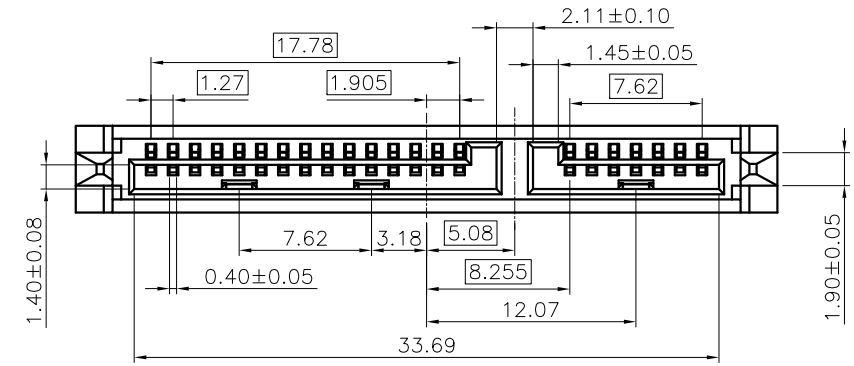
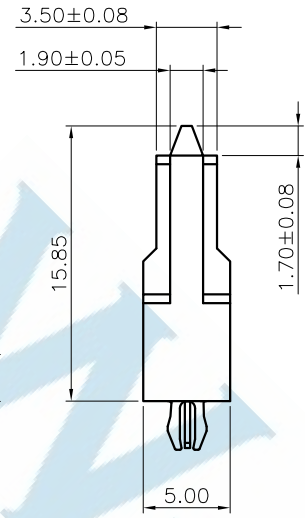
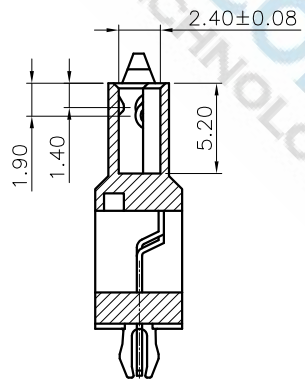


剖面圖A-A



RECOMMENDED PCB LAYOUT



NOTE:

- MATERIAL :  
 BASE : HIGH TEMPERATURE THERMOPLASTIC UL94V-0,  
 TERMINAL: COPPER ALLOY, THICKNESS = 0.30 mm  
 FORKLOCK: COPPER ALLOY, THICKNESS = 0.30 mm
- PLATING:  
 CONTACT: GOLD OVER 50u" MIN NICKEL UNDERPLATE  
 SOLDER TAIL: 150u" MIN MISTY TIN 50u" MIN NICKEL UNDERPLATE  
 GOLD SPECIFICATION: SEE TABLE
- ELECTRONICAL SPECIFICATION:  
 CURRENT RATING: 1.5 AMPERE PER CONTACT  
 CONTACT RESISTANCE: 30 MILLIOHMS MAX.  
 INSULATION RESISTANCE: 1000 MEGOHMS MIN.  
 DIELECTRIC WITHSTANDING VOLTAGE: 500 VDC.  
 OPERATING TEMPERATURE: -40°C ~ +85°C
- MEETS THE REQUIREMENTS OF DIRECTIVE 2002/95/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL OF 27 JANUARY 2003 ON THE RESTRICTION OF THE USE OF CERTAIN HAZARDOUS SUBSTANCES IN ELECTRICAL AND ELECTRONIC EQUIPMENT (ROHS)

DIMENSIONS TOLERANCE METRIC .0=±0.30 .00=±0.20 .000=±0.10 ANG.=±3°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME) SATA 22P 母座 直立式 H:14.15 單排 加高魚叉型	WISCONN Technology Co., Ltd Tel: 02-2742-1798 Fax: 02-2742-1898									
	數量(QTY)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena						料號(PART NUMBER)	WSTA-22xxLBDVS-14.15				
	材料(MTL)	SEE NOTE	設計(DE'N)	Mike	日期 DATE)	OCT.15.2007	圖號(DRAW NUMBER)	T006	圖檔(FILE NAME .DWG)		比例 (SCALE)	1/1	圖紙 (SIZE)	A4	頁次 (SHEET)	1	版次 (REV.)